



Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

IPC-1752-2 v1.02

IPC Web Site for Information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type *

Declaration Class *

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	Response Date *	Response Document ID				
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *					
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *		Supplier Comments or URL for Additional Information			
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
			C	seconds	

Comments

Save the fields in this form to a file

Import fields from a file into this form

Locked

RoHS Material Composition Declaration

Declaration Type *

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

RoHS Declaration *

Supplier Acceptance

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and checkboxes will appear below. Check all applicable exemptions.

- | | |
|--|--|
| 1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp. | 7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices). |
| 2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg in halophosphate lamps | 8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations piezoelectronic devices). |
| 2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal lifetime | 9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators |
| 2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg in triphosphate lamps with long lifetime | 10a. Deca BDE in polymeric applications |
| 3. Mercury in straight fluorescent lamps for special purposes. | 10b. Lead in lead-bronze bearing shells |
| 4. Mercury in other lamps not specifically mentioned in this list. | 11. Lead used in compliant pin connector systems. |
| 5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes. | 12. Lead as a coating material for a thermal conduction module c-ring. |
| 6a. Lead as an alloying element in steel containing up to 0.35% lead by weight. | 13a. Lead in optical and filter glass. |
| 6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight. | 13b. Cadmium in optical and filter glass. |
| 6c. Lead as an alloying element in copper containing up to 4% lead by weight. | 14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight . |
| 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). | 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages. |
| 7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications. | |

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

